



All needs in ceramic electronics

CT7025 Technical Data

Lead free low curing temperature silver composition end termination for
the application of a conductive base onto electronic component devices
which are barrier plated for surface mount application.

- Pastes Data:

Metal Content	70 ±2%
Sheet Resistivity	<150m Ω/□/25 μm
Viscosity	13 ±5Kcps.
Printing	Screen Printing: 325 SUS mesh, 10 μm emulsion
Curing	Method1: 1. Drying: 150 °C, 5~10 minutes 2. Curing: 180 °C/40 mins or 200 °C/30 mins or 230 °C/20 min Method2: Curing at 230 °C for 30 minutes
Storage	Material should be stored refrigerated or frozen in sealed containers.

E-mail: ceratek@msn.com

Get in touch with us today to get more information!!